

ABSTRACT OF THE DISCLOSURE

A sputtering target is provided, including a target material and a backing plate that are bonded with a strong adhesion at a reduced cost. The method for bonding the target material and the backing plate does not use a special soldering material, and is therefore cheaper and more reliable. The target includes an inorganic target material and a backing plate that are bonded with a soldering material between them. At least one of the target material and the backing plate is coated with a coupling agent of a semi-metal oxide or a metal oxide.